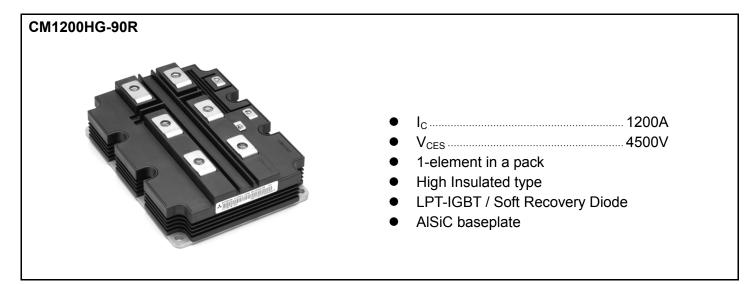


< HVIGBT MODULES > CM1200HG-90R

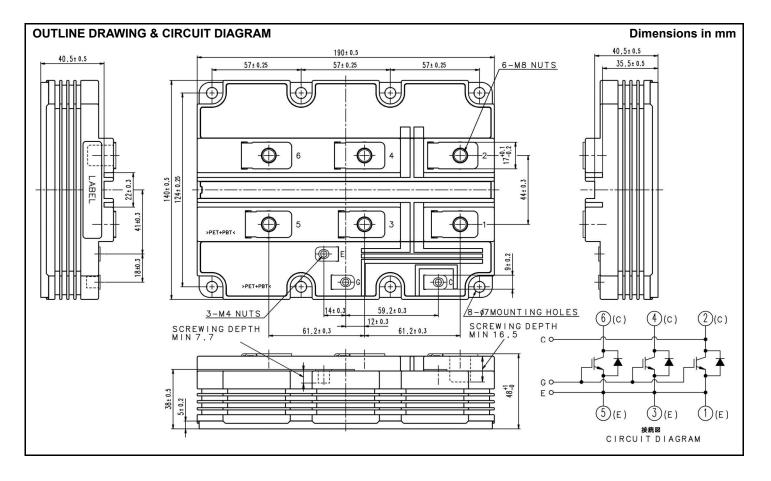
HIGH POWER SWITCHING USE INSULATED TYPE

4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules



APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers



4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
V_{CES}	Collector-emitter voltage	V _{GE} = 0V, T _j = -40+125°C	4500	v
		$V_{GE} = 0V, T_j = -50^{\circ}C$	4400	v
V_{GES}	Gate-emitter voltage	$V_{CE} = 0V, T_j = 25^{\circ}C$	± 20	V
lc	Collector overent	DC, $T_c = 85^{\circ}C$	1200	А
I _{CRM}	Collector current	Pulse (Note 1)	2400	А
I _E		DC	1200	А
I _{ERM}	Emitter current (Note 2)	Pulse (Note 1)	2400	А
P _{tot}	Maximum power dissipation (Note 3)	T _c = 25°C, IGBT part	11900	W
V _{iso}	Isolation voltage	RMS, sinusoidal, f = 60Hz, t = 1 min.	10200	V
Ve	Partial discharge extinction voltage	RMS, sinusoidal, f = 60Hz, $Q_{PD} \le 10 \text{ pC}$	3500	V
Tj	Junction temperature		-50 ~ +150	°C
T _{jop}	Operating junction temperature		-50 ~ +125	°C
T _{stg}	Storage temperature		-55 ~ +125	°C
t _{psc}	Short circuit pulse width	V_{CC} = 3200V, $V_{CE} \le V_{CES}$, V_{GE} =15V, T_j =125°C	10	μS

ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions			Limits		Unit
Symbol	item	Conditions		Min	Тур	Max	Unit
l Oellester er	Callester sutoff surrant	$V_{CE} = V_{CES}, V_{GE} = 0V$	T _j = 25°C	_	_	16.0	
ICES	I _{CES} Collector cutoff current		T _j = 125°C	_	16.0	_	mA
V _{GE(th)}	Gate-emitter threshold voltage	V _{CE} = 10 V, I _C = 120 mA, T _j = 25°C		5.8	6.3	6.8	V
I _{GES}	Gate leakage current	$V_{GE} = V_{GES}, V_{CE} = 0V, T_j = 25^{\circ}C$		-0.5	_	0.5	μA
Cies	Input capacitance	(1 - 10)(1)(1 - 0)(1 - 100)(1)		_	175.0	_	nF
C _{oes}	Output capacitance	V _{CE} = 10 V, V _{GE} = 0 V, f = 100 kHz T _i = 25°C		_	11.0	_	nF
Cres	Reverse transfer capacitance	$I_j = 25 C$		_	5.0	_	nF
Q_{G}	Total gate charge	V_{CC} = 2800V, I _C = 1200A, V_{GE} = ±15V		_	13.5	_	μC
V		I _C = 1200 A ^(Note 4)	T _j = 25°C	_	3.50	_	V
V _{CEsat}	Collector-emitter saturation voltage	V _{GE} = 15 V	T _j = 125°C	_	4.40	5.10	v
	Turn-on delay time	V _{CC} = 2800 V I _C = 1200 A V _{GE} = ±15 V	T _j = 25°C	_	1.00	_	
t _{d(on)}			T _j = 125°C	_	0.95	1.50	μs
	Turn-on rise time		T _j = 25°C	_	0.28	_	
t _r	rum-on rise time		T _j = 125°C	_	0.30	0.50	μs
-	Turn on quitching on quart (Note 5)	$R_{G(on)} = 2.7 \Omega$	T _j = 25°C	_	4.30	_	
E _{on(10%)}	Turn-on switching energy	L _s = 150 nH	T _j = 125°C	_	5.10	_	J
-	Turne on envitability on energy (Note 6)	Inductive load	T _j = 25°C	_	4.60	_	
Eon	Turn-on switching energy		T _j = 125°C	_	5.50	_	J
1	Turn off dolou times		T _j = 25°C	_	3.60	_	
$t_{d(off)}$	Turn-off delay time	V _{CC} = 2800 V	T _j = 125°C	_	3.80	5.00	μs
	T (() ,) ,)	I _C = 1200 A	T _j = 25°C	_	0.35	_	
t _f	Turn-off fall time	$V_{GE} = \pm 15 V$	T _j = 125°C	_	0.45	1.00	μs
-	Turn off quitabing aparaly (Note 5)	$R_{G(off)} = 10 \Omega$	T _j = 25°C	_	2.90	_	
E _{off(10%)}	Turn-off switching energy (Note 5)	L _s = 150 nH	T _j = 125°C	_	3.85	_	J
F	Turn off quitching operation (Note 6)	Inductive load	T _j = 25°C	_	3.20	_	
E _{off}	Turn-off switching energy		T _j = 125°C	_	4.30	_	J

4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

Symbol	Item		Conditions			Limits		Unit
Symbol	itelli			Min	Тур	Max	Unit	
V _{FC}	Emitter-collector voltage	e 2)	I _E = 1200 A ^(Note 4)	T _j = 25°C		2.50	_	V
VEC	Enlitter-collector voltage		$V_{GE} = 0 V$	T _j = 125°C		2.80	3.40	v
+	Reverse recovery time (Note 2)	ote 2)	V _{cc} = 2800 V	T _j = 25°C	_	0.70	_	
t _{rr}				T _j = 125°C		0.90	_	μs
	(Note 2)	ote 2)		T _j = 25°C		1100	_	А
Im	Reverse recovery current		I _C = 1200 A	T _i = 125°C		1200	_	A
Q _{rr}	Reverse recovery charge (Note 2)	ote 2)	$V_{GE} = \pm 15 V$	T _j = 25°C		1000	_	μC
Qrr	Reverse recovery charge		$R_{G(on)} = 2.7 \Omega$	T _j = 125°C	_	1500	_	μΟ
-	Reverse recovery energy (No	ote 2)	L _s = 150 nH	T _j = 25°C		1.30	_	-
Erec(10%)	(No	ote 5)	Inductive load	T _i = 125°C		2.10	_	J
F	Reverse recovery energy (No	ote 2)		T _j = 25°C	_	1.55	_	
E _{rec}	(No	ote 6)		T _j = 125°C	_	2.40	_	J

ELECTRICAL CHARACTERISTICS (continuation)

THERMAL CHARACTERISTICS

Symbol	Item	Conditions		Limits		
				Тур	Max	Unit
R _{th(j-c)Q}	Thermal resistance	Junction to Case, IGBT part			10.5	K/kW
R _{th(j-c)D}		Junction to Case, FWDi part			19.5	K/kW
R _{th(c-s)}	Contact thermal resistance	Case to heat sink, $\lambda_{grease} = 1W/m \cdot k$, $D_{(c-s)} = 100 \mu m$		6.0	_	K/kW

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Тур	Max	Unit
Mt		M8 : Main terminals screw	7.0		22.0	N∙m
Ms	Mounting torque	M6 : Mounting screw	3.0		6.0	N∙m
Mt		M4 : Auxiliary terminals screw	1.0		3.0	N∙m
m	Mass		—	1.4		kg
CTI	Comparative tracking index		600		_	_
d _a	Clearance		26.0		_	mm
ds	Creepage distance		56.0			mm
L _{P CE}	Parasitic stray inductance		—	15.0	_	nH
R _{CC'+EE'}	Internal lead resistance	$T_{\rm C} = 25^{\circ}{\rm C}$	—	0.18	_	mΩ
r _g	Internal gate resistance	$T_{\rm C} = 25^{\circ}{\rm C}$	_	1.7	_	Ω

Note1. Pulse width and repetition rate should be such that junction temperature (T_j) does not exceed T_{jopmax} rating.

2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWD_i).

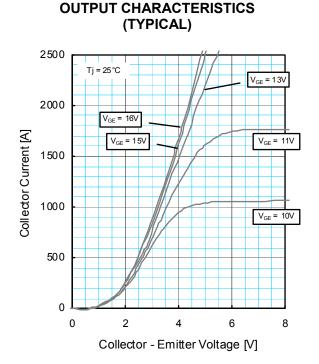
3. Junction temperature (T_j) should not exceed T_{jmax} rating (150°C).

4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

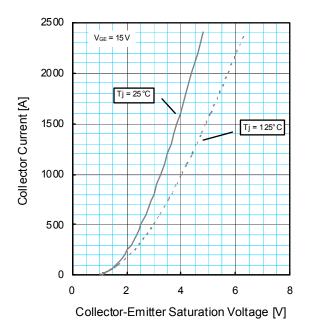
5. $E_{on(10\%)}$ / $E_{off(10\%)}$ / $E_{rec(10\%)}$ are the integral of 0.1V_{CE} x 0.1I_C x dt.

6. Definition of all items is according to IEC 60747, unless otherwise specified.

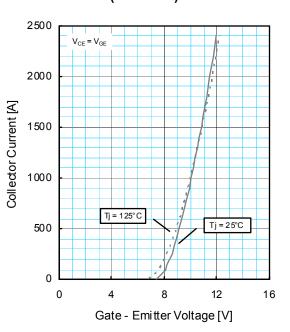
PERFORMANCE CURVES



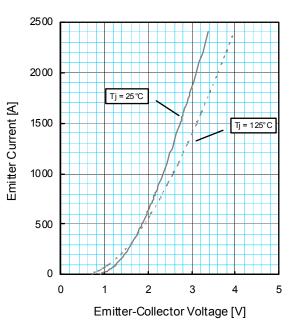
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



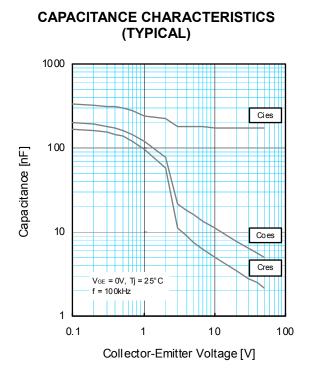
TRANSFER CHARACTERISTICS (TYPICAL)



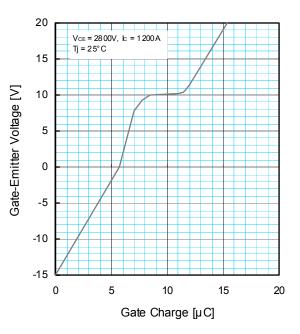
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



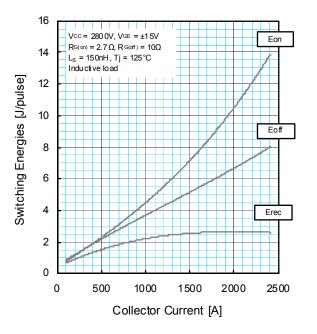
PERFORMANCE CURVES



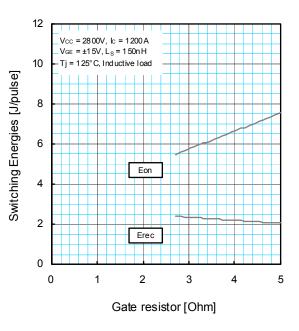
GATE CHARGE CHARACTERISTICS (TYPICAL)



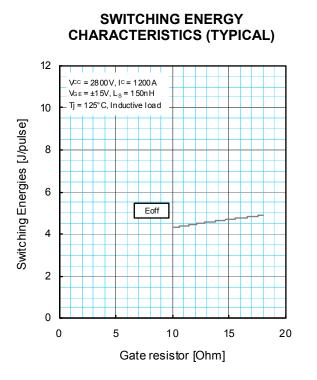
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



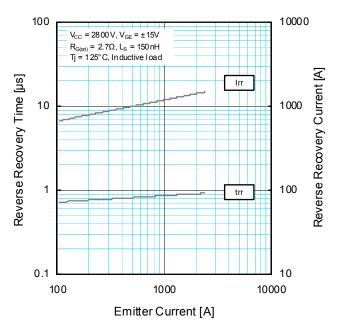
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



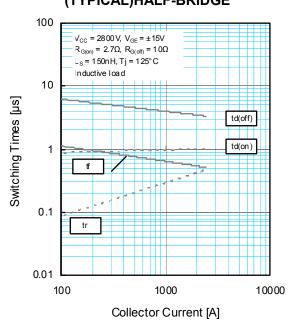
PERFORMANCE CURVES



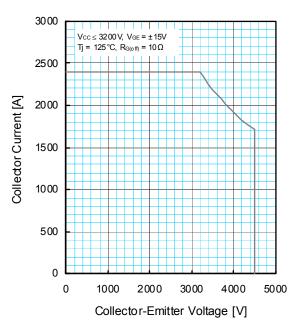
FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



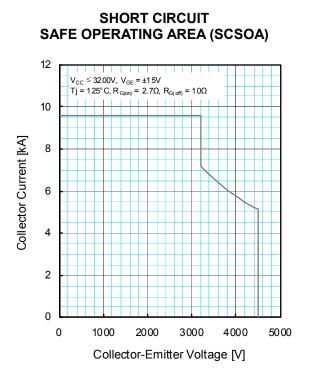
HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)HALF-BRIDGE



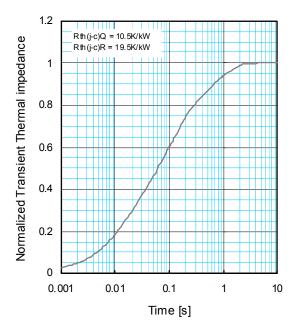
REVERSE BIAS SAFE OPERATING AREA (RBSOA)



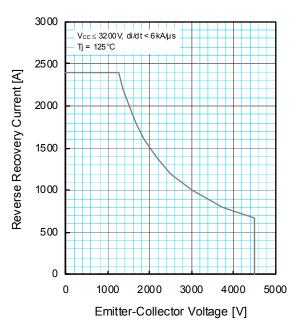
PERFORMANCE CURVES

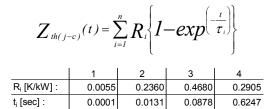


TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS



FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)





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